

Experimental study of humidity and temperature profile into electronic enclosure exposed to high humidity and thermal cycles - DTU Orbit (09/11/2017)

Experimental study of humidity and temperature profile into electronic enclosure exposed to high humidity and thermal cycles

General information

State: Published

Organisations: Department of Mechanical Engineering, Materials and Surface Engineering

Authors: Conseil, H. (Intern), Jellesen, M. S. (Intern), Ambat, R. (Intern)

Pages: 111-117

Publication date: 2015

Host publication information

Title of host publication: Proceedings of the IMAPS Nordic Annual Conference 2015

Publisher: International Microelectronics and packaging Society

Editor: Kutilainen, J.

ISBN (Print): 9781510808133

Main Research Area: Technical/natural sciences

Conference: IMAPS Nordic Annual Conference 2015, Helsingør, Denmark, 08/06/2015 - 08/06/2015

Humidity, Temperature, Electronic materials, Enclosures, Internal climate, Electronic reliability

Source: PublicationPreSubmission

Source-ID: 123637769

Publication: Research - peer-review › Article in proceedings – Annual report year: 2016